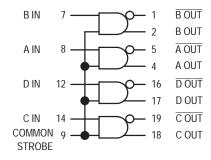
Quad TTL/NMOS to PECL* Translator

The MC10H351 is a quad translator for interfacing data between a saturated logic section and the PECL section of digital systems when only a +5.0 Vdc power supply is available. The MC10H351 has TTL/NMOS compatible inputs and PECL complementary open—emitter outputs that allow use as an inverting/non—inverting translator or as a differential line driver. When the common strobe input is at a low logic level, it forces all true outputs to the PECL low logic state (\approx +3.2 V) and all inverting outputs to the PECL high logic state (\approx +4.1 V).

The MC10H351 can also be used with the MC10H350 to transmit and receive TTL/NMOS information differentially via balanced twisted pair lines.

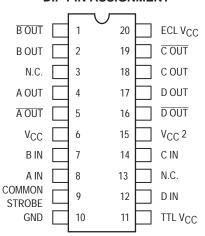
- Single +5.0 Power Supply
- All V_{CC} Pins Isolated On Chip
- Differentially Drive Balanced Lines
- $t_{pd} = 1.3$ nsec Typical

LOGIC DIAGRAM



V_{CC} (+5.0 VDC) = PINS 6, 11, 15, 20 GND = PIN 10

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



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MARKING DIAGRAMS



CDIP-20 L SUFFIX CASE 732





PDIP-20 P SUFFIX CASE 738





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H351L	CDIP-20	18 Units/Rail
MC10H351P	PDIP-20	18 Units/Rail
MC10H351FN	PLCC-20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
Vcc	Power Supply	0 to +7.0	Vdc
VI	Input Voltage (V _{CC} = 5.0 V)	0 to V _{CC}	Vdc
l _{out}	Output Current – Continuous – Surge	50 100	mA
TA	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C

ELECTRICAL CHARACTERISTICS ($V_{CC} = V_{CC1} = V_{CC2} = 5.0 \text{ V} \pm 5.0\%$)†

		0° 25°		5°	~ 75°			
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ECL	Power Supply		50	_	45	-	50	mA
TTL	Current	-	20	_	15	-	20	mA
I _R	Reverse Current Pins 7, 8, 12, 14 Pin 9	- -	25 100	- -	20 80	- -	25 100	μΑ
I _F	Forward Current Pins 7, 8, 12, 14 Pin 9	_ _	-0.8 -3.2	- -	-0.6 -2.4	- -	-0.8 -3.2	mA
V _{(BR)in}	Input Breakdown Voltage	5.5	-	5.5	-	5.5	-	Vdc
VI	Input Clamp Voltage (I _{in} = -18 mA)	-	-1.5	_	-1.5	-	-1.5	Vdc
VOH	High Output Voltage (Note 1.)	3.98	4.16	4.02	4.19	4.08	4.27	Vdc
VOL	Low Output Voltage (1)	3.05	3.37	3.05	3.37	3.05	3.37	Vdc
VIH	High Input Voltage	2.0	-	2.0	-	2.0	-	Vdc
VIL	Low Input Voltage	-	0.8	-	0.8	-	0.8	Vdc

^{1.} With V_{CC} at 5.0 V. V_{OH}/V_{OL} change 1:1 with V_{CC}.

AC PARAMETERS

		0° 25°		75°				
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay (Note 2)	0.4	2.2	0.4	2.2	0.4	2.1	ns
t _r	Rise Time (20% to 80%)	0.4	1.9	0.4	2.0	0.4	2.1	ns
t _f	Fall Time (80% to 20%)	0.4	1.9	0.4	2.0	0.4	2.1	ns
f _{max}	Maximum Operating Frequency	150	_	150	-	150	_	MHz

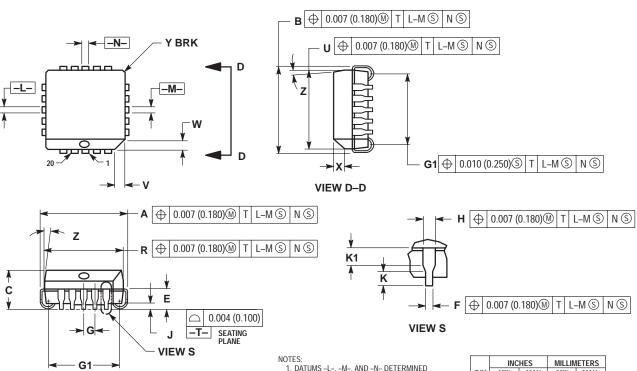
^{2.} Propagation delay is measured on this circuit from +1.5 volts on the input waveform to the 50% point on the output waveform. †Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been

^{*}Positive Emitter Coupled Logic

established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50–ohm resistor to V_{CC} –2.0 Vdc.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑥

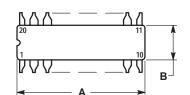
- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

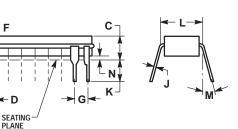
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD.
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE. 4. DIMENSIONING AND TOLERANCING PER ANSI
- 4. DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH. 6. THE PACKAGE TOP MAY BE SMALLER THAN THE
- PACKAGE BOTTOM BY UP TO 0.012 (0.300).
 DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMAICH BE I WEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

CDIP-20 **L SUFFIX** CERAMIC DIP PACKAGE CASE 732-03 ISSUE E





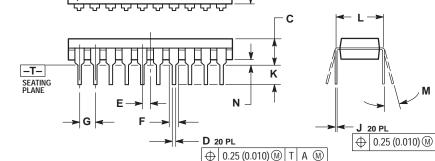
B

- 1 LEADS WITHIN 0.010 DIAMETER TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
- 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL
- 3. DIMENSIONS A AND B INCLUDE MENISCUS.

	INCHES				
DIM	MIN	MAX			
Α	0.940	0.990			
В	0.260	0.295			
С	0.150	0.200			
D	0.015	0.022			
F	0.055	0.065			
G	0.100 BSC				
Н	0.020	0.050			
J	0.008	0.012			
K	0.125	0.160			
L	0.300 BSC				
M	0°	15°			
N	0.010	0.040			

PDIP-20 **P SUFFIX**

PLASTIC DIP PACKAGE CASE 738-03 ISSUE E



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
- 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.010	1.070	25.66	27.17	
В	0.240	0.260	6.10	6.60	
С	0.150	0.180	3.81	4.57	
D	0.015	0.022	0.39	0.55	
Ε	0.050	BSC	1.27 BSC		
F	0.050	0.070	1.27	1.77	
G	0.100	BSC	2.54 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.140	2.80	3.55	
L	0.300 BSC		7.62 BSC		
M	0°	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

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